

L Number	Hits	Search Text	DB	Time stamp
1	3	359/350.ccls. and 385/14,88-94.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/06 13:55
2	144	(385/14,88-94.ccls. or 359/350.ccls.) and (infrared or infra-red) near5 (module or apparatus or device))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/06 13:55
3	214	385/92,94.ccls. and substrate and (light or optic or optical) and mold\$7	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/06 13:55
4	176	((gold and (mold\$5 near4 resin\$6) and substrate and emit\$8 and receiv\$7) and (seal\$8 or cover\$6 or protect\$6)) and (housing or module)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/06 13:56
5	106	((die near5 bond\$8 near4 pad\$6) and substrate and gold) and (module or housing)) and emit\$7	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/06 13:56
6	58	shimonaka-atsumi.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/06 13:56
7	129	((385/14,88-94.ccls. or 359/154,350.ccls. or 398/140,164.ccls.) and substrate and (transmi\$7 or emit\$7) and receiv\$8) and (mold\$8 near4 resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/06 14:34
8	150	(die near3 bond\$7 near4 pad) and (gold near3 plat\$7) and (transmi\$7 or emit\$7)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/06 14:36